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United States Patent [19] Orth

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[54] **PROCESS AND SYSTEM FOR FLATTENING SECONDARY EDGEHEADS ON RESIST COATED WAFERS**

[56] **References Cited**

U.S. PATENT DOCUMENTS

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[21] Appl. No.: **989,893**

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[22] Filed: **Dec. 12, 1997**

[57] **ABSTRACT**

Related U.S. Application Data

[62] Division of Ser. No. 306,920, Sep. 16, 1994, Pat. No. 5,750,317.

[51] **Int. Cl.**⁶ **G03F 7/16**

[52] **U.S. Cl.** **430/327; 430/311; 134/33; 427/240; 427/273**

[58] **Field of Search** 430/311, 313, 430/317, 322, 325, 327, 328, 331; 134/33, 34, 38; 427/532, 240, 336, 273

A method and system of flattening resist mounds formed during a wet edgebead operation. The wet edgebead operation is used to remove edgebeads formed when a resist material is deposited on a semiconductor wafer. Solvent is introduced to the semiconductor wafer at the area containing the resist mounds to soften them, and the semiconductor wafer is spun at a high speed to flatten the mounds.

13 Claims, 7 Drawing Sheets

